

isc N-Channel MOSFET Transistor

IPD90R1K2C3,IIPD90R1K2C3

• FEATURES

- Static drain-source on-resistance:
 $R_{DS(on)} \leq 1.2\Omega$
- Enhancement mode:
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• DESCRIPTION

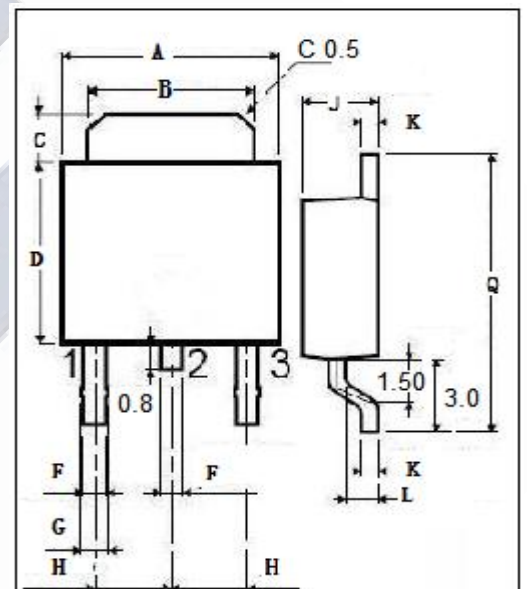
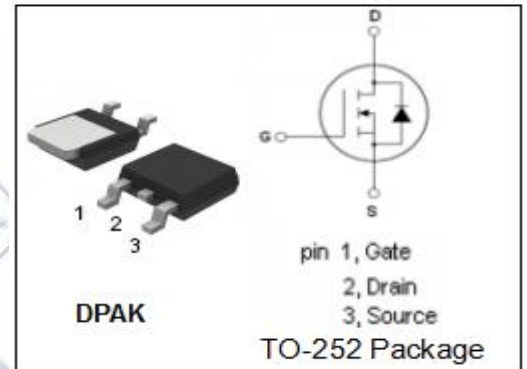
- High peak current capability

• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DS}	Drain-Source Voltage	900	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous	5.1	A
I_{DM}	Drain Current-Single Pulsed	10	A
P_D	Total Dissipation @ $T_c=25^\circ\text{C}$	83	W
T_j	Max. Operating Junction Temperature	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~150	$^\circ\text{C}$

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(j-c)}$	Channel-to-case thermal resistance	1.5	$^\circ\text{C/W}$
$R_{th(j-a)}$	Channel-to-ambient thermal resistance	62	$^\circ\text{C/W}$



DIM	MIN	MAX
A	6.40	6.60
B	5.20	5.40
C	1.15	1.35
D	5.70	6.10
E	0.65	
F	0.75	
G	2.10	2.50
H	2.10	2.40
J	0.40	0.60
K	0.90	1.10
L	9.90	10.1

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ELECTRICAL CHARACTERISTICS

$T_C=25^{\circ}\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DS}	Drain-Source Breakdown Voltage	$V_{GS}=0V; I_D=0.25mA$	900			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}; I_D=0.31mA$	2.5		3.5	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=10V; I_D=2.8A$			1.2	Ω
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=20V; V_{DS}=0V$			0.1	μA
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=900V; V_{GS}=0V$			1	μA
V_{SD}	Diode forward voltage	$I_F=2.8A, V_{GS}=0V$			1.2	V